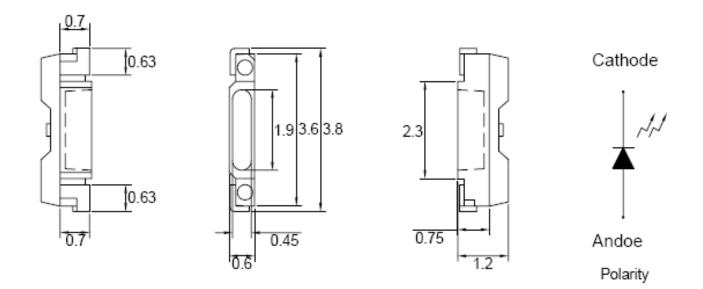
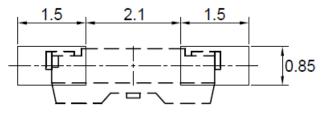


3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

PACKAGE OUTLINES



RECOMMEND PAD LAYOUT



NOTES:

1. All dimensions are in millimeters tolerance is ±0.2mm unless otherwise noted; Angle±0.5. Unit=mm.

Part Number	Material	Lens Color	
		Emitted	Lens
L234NEC-TR	AlGaInP	Red	Water Clear



3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

ABSOLUTE MAXIMUM RATINGS	(Ta=25°C)		
Parameter	Symbol	Ratings	Unit
Power Dissipation	PD	72	mW
Peak Forward Current (Duty 1/11@10KHz)	lfp	60	mA
Forward Current	lf	30	mA
Reverse Current @ 5V	Ir	10	μA
Electrostatic Discharge	ESD	2000	V
Operating temperature range	Topr	-40~+85	°C
Storage temperature range	Tstg	-40~+100	°C

OPTICAL-ELECTRICAL CHARACTERISTICS

(Ta=25°C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	I _F =20mA	200	320		mcd
Dominant Wavelength	λD			625		nm
Spectral Line Half-Width	Δλ			20		nm
Forward Voltage	Vf		1.5		2.4	V
Viewing angle	20 1⁄2			120		Deg

*Note: 1. The forward voltage data did not include $\pm 0.1V$ testing tolerance.

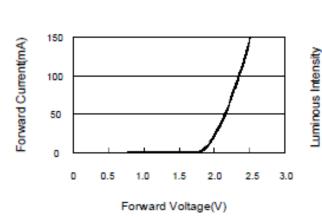
2. The luminous intensity data did not include $\pm 15\%$ testing tolerance.



3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES

Fig.1 Forward current vs. Forward Voltage



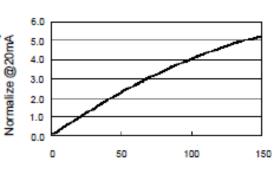
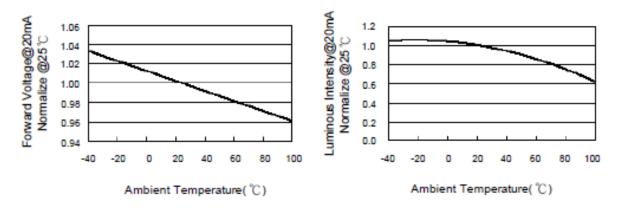


Fig.2 Luminous Intensity vs. Forward Current

Forward Current(mA)

Fig.3 Forward Voltage vs. Temperature

Fig.4 Luminous Intensity vs. Temperature





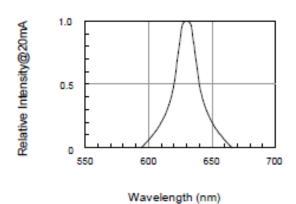
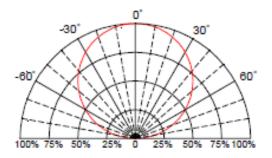


Fig.6 Directive Radiation





3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

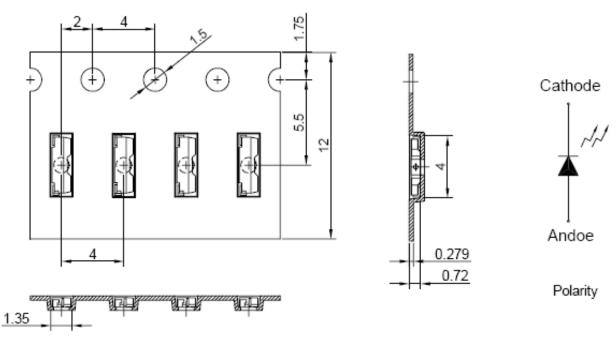
LUMINOUS INTENSITY CLASSIFICATION

BIN CODE	lv(mcd)	@ 20mA
BINCODE	Min.	Max.
S	200	320
т	320	500
U	500	800



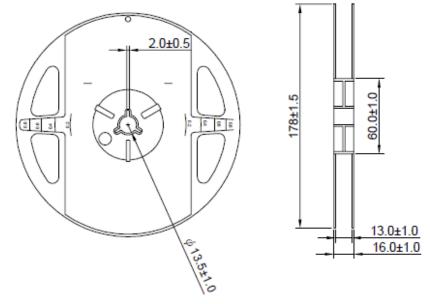
3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

CARRIER TAPE DIMENSION



Note: The tolerances unless mentioned are ±0.1mm, Angle ±0.5; Unit=mm

REEL DIMENSIONS



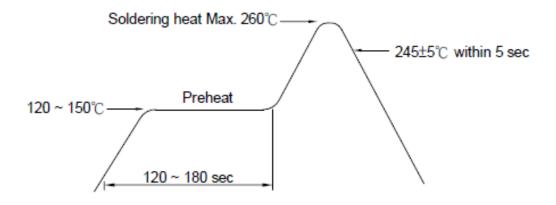
Notes: 1. 3000 pieces per reel.



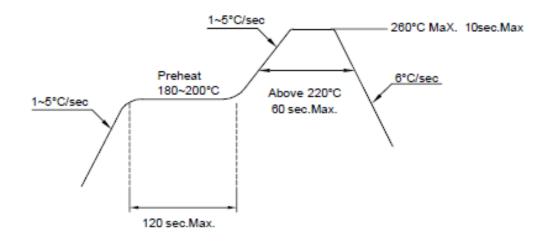
3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

RECOMMENDED SOLDERING CONDITIONS

- Hand solder Basic spec is ≤ 320°C 3 sec one time only.
- 2. Wave solder



3. PB-Free reflow solder



Notes:

- 1. Reflow soldering should not be done more than two times.
- 2. When soldering, do not put stress on the LEDs during heating.
- 3. After soldering, do not warp the circuit board.



3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

PRECAUTIONS FOR USE

Storage Time:

1. The operation of temperatures and RH are: 5°C~35°C, RH60%.

2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with descanting agent. Considering the tape life, we suggest our customers to use our products within a year (from production date).

3. If opened more than one week in an atmosphere 5°C~35°C, RH60%, they should be treated at 60°C±5°C for 15hrs.

Drive Method:

LED is a current operated device, and therefore, require some kind of current limiting incorporated into the driver circuit. This current limiting typically takes the form of a current limiting resistor placed in a series with the LED.

Consider worst case voltage variations that could occur across the current limiting resistor. The forward current should not be allowed to change by more than 40% of its desired value.



(A) Recommended circuit.

(B) The difference of brightness between LED could be found due to the VF-IF characteristics of LED.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED.

ESD(Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or antielectrostatic glove is recommended when handling these LEDs. All devices and machinery must be properly grounded.



3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

RELIABILITY TEST:

(1) Test items and results

Classification	Test Item	Test Conditions	Number of Damaged
	Operating Life Test	 Ta=under room temperature as per data sheet maximum rating If=20mA t=1000 hrs 	0/22
ice Test	High Temperature Storage Test	1. Ta=105°C±5°C 2. t=500 hrs	0/22
Endurance Test	Low Temperature Storage Test	1. Ta=40°C±5°C 2. t=1000 hrs	0/22
	High Temperature High Humidity Storage Test	1. IR-Reflow in-board, 2 times 2. Ta=85°C±5°C 3. RH=90%~95% 4. t=500hrs±2hrs	0/22
Environmental Test	Thermal Shock Test	 IR-Reflow in-board, 2 times Ta=105°C±5°C & -40°C±5°C (30min) (30min) Total 100 cycles 	0/22
	Reflow Soldering Test	1. Tsol=260°C±5°C 2. Dwell time = 10 max	0/22
	Temperature Cycling	1. 105°C ~ 25°C ~ -40°C 30 mins 15 mins 30 mins 2. 100 cycles	0/22

(2) Criteria for judging the damage

Itom	Qumbal	Test Conditions	Criteria for Judgement		
Item Symbol		Test Conditions	Min.	Max.	
Forward Voltage	Vf	lf=20mA		U.S.L. x 1.2	
Reverse Current	lr	Vr=5V		U.S.L. x 2.0	
Luminous Intensity	lv	lf=20mA	L.S.L. x 0.5	-	

Note:

1. U.S.L.: Upper Standard Level. 2. L.S.L: Lower Standard Level